

# Two Output Differential Buffer for PCIe Gen3

# 9DB233

**Recommended Application:**

2 output PCIe Gen3 zero-delay/fanout buffer

**General Description:**

The 9DB233 zero-delay buffer supports PCIe Gen3 requirements, while being backwards compatible to PCIe Gen2 and Gen1. The 9DB233 is driven by a differential SRC output pair from an IDT 932S421 or 932SQ420 or equivalent main clock generator. It attenuates jitter on the input clock and has a selectable PLL bandwidth to maximize performance in systems with or without Spread-Spectrum clocking. An SMBus interface allows control of the PLL bandwidth and bypass options, while 2 clock request (OE#) pins make the 9DB233 suitable for Express Card applications.

**Key Specifications:**

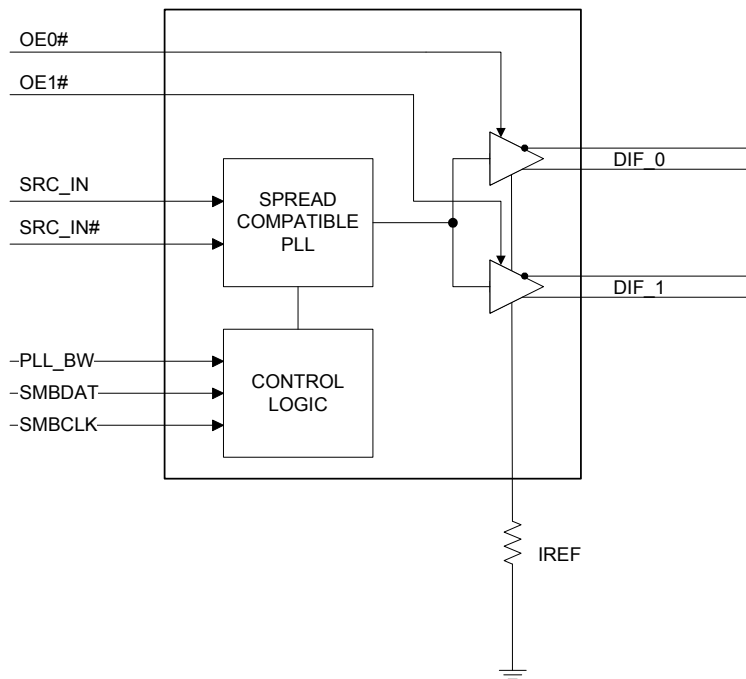
- Cycle-to-cycle jitter < 50 ps
- Output-to-output skew < 50 ps
- PCIe Gen3 phase jitter < 1.0ps RMS

**Features/Benefits:**

- OE# pins/Suitable for Express Card applications
- PLL or bypass mode/PLL can dejitter incoming clock
- Selectable PLL bandwidth/minimizes jitter peaking in downstream PLL's
- Spread Spectrum Compatible/tracks spreading input clock for low EMI
- SMBus Interface/unused outputs can be disabled

**Output Features:**

- 2 - 0.7V current mode differential output pairs (HSCL)

**Block Diagram**


Pin Configuration

PLL_BW	1	<b>9DB233</b>	20	VDDA
SRC_IN	2		19	GNDA
SRC_IN#	3		18	IREF
vOE0#	4		17	vOE1#
VDD	5		16	VDD
GND	6		15	GND
DIF_0	7		14	DIF_1
DIF_0#	8		13	DIF_1#
VDD	9		12	VDD
SMBDAT	10		11	SMBCLK

**Note:** Pins preceded by ' v ' have internal 120K ohm pull down resistors

Power Distribution Table

Pin Number		Description
VDD	GND	
5,9,12,16	6,15	Differential Outputs
9	6	SMBUS
20	19	IREF
20	19	Analog VDD & GND for PLL core

## Pin Description

PIN #	PIN NAME	PIN TYPE	DESCRIPTION
1	PLL_BW	IN	3.3V input for selecting PLL Band Width 0 = low, 1= high
2	SRC_IN	IN	0.7 V Differential SRC TRUE input
3	SRC_IN#	IN	0.7 V Differential SRC COMPLEMENTARY input
4	vOE0#	IN	Active low input for enabling DIF pair 0. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
5	VDD	PWR	Power supply, nominal 3.3V
6	GND	PWR	Ground pin.
7	DIF_0	OUT	0.7V differential true clock output
8	DIF_0#	OUT	0.7V differential Complementary clock output
9	VDD	PWR	Power supply, nominal 3.3V
10	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant
11	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant
12	VDD	PWR	Power supply, nominal 3.3V
13	DIF_1#	OUT	0.7V differential Complementary clock output
14	DIF_1	OUT	0.7V differential true clock output
15	GND	PWR	Ground pin.
16	VDD	PWR	Power supply, nominal 3.3V
17	vOE1#	IN	Active low input for enabling DIF pair 1. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
18	IREF	OUT	This pin establishes the reference for the differential current-mode output pairs. It requires a fixed precision resistor to ground. 475ohm is the standard value for 100ohm differential impedance. Other impedances require different values. See data sheet.
19	GND A	PWR	Ground pin for the PLL core.
20	VDD A	PWR	3.3V power for the PLL core.

### Note:

Pins preceded by ' v ' have internal 120K ohm pull down resistors

**Electrical Characteristics - Absolute Maximum Ratings**

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
3.3V Core Supply Voltage	VDDA				4.6	V	1,2
3.3V Logic Supply Voltage	VDD				4.6	V	1,2
Input Low Voltage	V <sub>IL</sub>		GND-0.5			V	1
Input High Voltage	V <sub>IH</sub>	Except for SMBus interface			V <sub>DD</sub> +0.5V	V	1
Input High Voltage	V <sub>IHSMB</sub>	SMBus clock and data pins			5.5V	V	1
Storage Temperature	T <sub>s</sub>		-65		150	°C	1
Junction Temperature	T <sub>j</sub>				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Operation under these conditions is neither implied nor guaranteed.

**Electrical Characteristics - Input/Supply/Common Parameters**

T<sub>A</sub> = T<sub>COM</sub> or T<sub>IND</sub>; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Ambient Operating Temperature	T <sub>COM</sub>	Commercial range	0		70	°C	1
	T <sub>IND</sub>	Industrial range	-40		85	°C	1
Input High Voltage	V <sub>IH</sub>	Single-ended inputs, except SMBus, low threshold and tri-level inputs	2		V <sub>DD</sub> + 0.3	V	1
Input Low Voltage	V <sub>IL</sub>	Single-ended inputs, except SMBus, low threshold and tri-level inputs	GND - 0.3		0.8	V	1
Input Current	I <sub>IN</sub>	Single-ended inputs, V <sub>IN</sub> = GND, V <sub>IN</sub> = VDD	-5		5	uA	1
	I <sub>INP</sub>	Single-ended inputs V <sub>IN</sub> = 0 V; Inputs with internal pull-up resistors V <sub>IN</sub> = VDD; Inputs with internal pull-down resistors	-200		200	uA	1
Input Frequency	F <sub>ibyp</sub>	V <sub>DD</sub> = 3.3 V, Bypass mode	10		110	MHz	2
	F <sub>ipll</sub>	V <sub>DD</sub> = 3.3 V, 100MHz PLL mode	33	100.00	110	MHz	2
Pin Inductance	L <sub>pin</sub>				7	nH	1
Capacitance	C <sub>IN</sub>	Logic Inputs, except DIF_IN	1.5		5	pF	1
	C <sub>INDIF_IN</sub>	DIF_IN differential clock inputs	1.5		2.7	pF	1,4
	C <sub>OUT</sub>	Output pin capacitance			6	pF	1
Clk Stabilization	T <sub>STAB</sub>	From V <sub>DD</sub> Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock			1.8	ms	1,2
Input SS Modulation Frequency	f <sub>MODIN</sub>	Allowable Frequency (Triangular Modulation)	30		33	kHz	1
OE# Latency	t <sub>LATOE#</sub>	DIF start after OE# assertion DIF stop after OE# deassertion	1		3	cycles	1,3
Tdrive_PD#	t <sub>DRVPD</sub>	DIF output enable after PD# de-assertion			300	us	1,3
Tfall	t <sub>F</sub>	Fall time of control inputs			5	ns	1,2
Trise	t <sub>R</sub>	Rise time of control inputs			5	ns	1,2
SMBus Input Low Voltage	V <sub>ILSMB</sub>				0.8	V	1
SMBus Input High Voltage	V <sub>IHSMB</sub>		2.1		V <sub>DDSMB</sub>	V	1
SMBus Output Low Voltage	V <sub>OLSMB</sub>	@ I <sub>PULLUP</sub>			0.4	V	1
SMBus Sink Current	I <sub>PULLUP</sub>	@ V <sub>OL</sub>	4			mA	1
Nominal Bus Voltage	V <sub>DDSMB</sub>	3V to 5V +/- 10%	2.7		5.5	V	1
SCLK/SDATA Rise Time	t <sub>RSMB</sub>	(Max V <sub>IL</sub> - 0.15) to (Min V <sub>IH</sub> + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t <sub>FSMB</sub>	(Min V <sub>IH</sub> + 0.15) to (Max V <sub>IL</sub> - 0.15)			300	ns	1
SMBus Operating Frequency	f <sub>MAXSMB</sub>	Maximum SMBus operating frequency			100	kHz	1,5

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Control input must be monotonic from 20% to 80% of input swing.

<sup>3</sup>Time from deassertion until outputs are >200 mV

<sup>4</sup>DIF\_IN input

<sup>5</sup>The differential input clock must be running for the SMBus to be active

**Electrical Characteristics - Clock Input Parameters**T<sub>A</sub> = T<sub>COM</sub> or T<sub>IND</sub>; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage - DIF_IN	V <sub>IHDIF</sub>	Differential inputs (single-ended measurement)	600	800	1150	mV	1
Input Low Voltage - DIF_IN	V <sub>ILDIF</sub>	Differential inputs (single-ended measurement)	V <sub>SS</sub> - 300	0	300	mV	1
Input Common Mode Voltage - DIF_IN	V <sub>COM</sub>	Common Mode Input Voltage	300		1000	mV	1
Input Amplitude - DIF_IN	V <sub>SWING</sub>	Peak to Peak value	300		1450	mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>DD</sub> , V <sub>IN</sub> = GND	-5		5	uA	1
Input Duty Cycle	d <sub>in</sub>	Measurement from differential waveform	45		55	%	1
Input Jitter - Cycle to Cycle	J <sub>DIFn</sub>	Differential Measurement	0		125	ps	1

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.<sup>2</sup> Slew rate measured through +/-75mV window centered around differential zero**Electrical Characteristics - DIF 0.7V Current Mode Differential Outputs**T<sub>A</sub> = T<sub>COM</sub> or T<sub>IND</sub>; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	Trf	Scope averaging on	0.6	2.5	4	V/ns	1, 2, 3
Slew rate matching	ΔTrf	Slew rate matching, Scope averaging on		9.5	20	%	1, 2, 4
Voltage High	VHigh	Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on)	660	740	850	mV	1
Voltage Low	VLow		-150	8	150		1
Max Voltage	Vmax	Measurement on single ended signal using absolute value. (Scope averaging off)		760	1150	mV	1
Min Voltage	Vmin		-300	-3			1
Vswing	Vswing	Scope averaging off	300	1506		mV	1, 2
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	250	378	550	mV	1, 5
Crossing Voltage (var)	ΔVcross	Scope averaging off		54	140	mV	1, 6

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production. I<sub>REF</sub> = VDD/(3xR<sub>R</sub>). For R<sub>R</sub> = 475Ω (1%), I<sub>REF</sub> = 2.32mA. I<sub>OH</sub> = 6 x I<sub>REF</sub> and V<sub>OH</sub> = 0.7V @ Z<sub>O</sub>=50Ω (100Ω differential impedance).<sup>2</sup> Measured from differential waveform<sup>3</sup> Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.<sup>4</sup> Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.<sup>5</sup> Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).<sup>6</sup> The total variation of all Vcross measurements in any particular system. Note that this is a subset of V\_cross\_min/max (V\_cross absolute) allowed. The intent is to limit Vcross induced modulation by setting V\_cross\_delta to be smaller than V\_cross absolute.**Electrical Characteristics - Current Consumption**T<sub>A</sub> = T<sub>COM</sub> or T<sub>IND</sub>; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	I <sub>DD3.30P</sub>	All outputs active @100MHz, C <sub>L</sub> = Full load;		70	80	mA	1
Powerdown Current	I <sub>DD3.3PD</sub>	All diff pairs driven			N/A	mA	1
	I <sub>DD3.3PDZ</sub>	All differential pairs tri-stated			N/A	mA	1

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

### Electrical Characteristics - Output Duty Cycle, Jitter, Skew and PLL Characteristics

TA = T<sub>COM</sub> or T<sub>IND</sub>; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
PLL Bandwidth	BW	-3dB point in High BW Mode	2	2.3	4	MHz	1
		-3dB point in Low BW Mode	0.4	0.5	1	MHz	1
PLL Jitter Peaking	t <sub>JPEAK</sub>	Peak Pass band Gain		1	2	dB	1
Duty Cycle	t <sub>DC</sub>	Measured differentially, PLL Mode	45	48	55	%	1
Duty Cycle Distortion	t <sub>DCD</sub>	Measured differentially, Bypass Mode @100MHz	-2	1	2	%	1,4
Skew, Input to Output	t <sub>pdBYP</sub>	Bypass Mode, V <sub>T</sub> = 50%	2500	3660	4500	ps	1
	t <sub>pdPLL</sub>	Hi BW PLL Mode V <sub>T</sub> = 50%	-250	0	250	ps	1
Skew, Output to Output	t <sub>sk3</sub>	V <sub>T</sub> = 50%		15	50	ps	1
Jitter, Cycle to cycle	t <sub>jyc-cyc</sub>	PLL mode		40	50	ps	1,3
		Additive Jitter in Bypass Mode		10	50	ps	1,3

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>I<sub>REF</sub> = V<sub>DD</sub>/(3xR<sub>R</sub>). For R<sub>R</sub> = 475Ω (1%), I<sub>REF</sub> = 2.32mA. I<sub>OH</sub> = 6 x I<sub>REF</sub> and V<sub>OH</sub> = 0.7V @ Z<sub>O</sub>=50Ω.

<sup>3</sup>Measured from differential waveform

<sup>4</sup>Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

### Electrical Characteristics - PCIe Phase Jitter Parameters

TA = T<sub>COM</sub> or T<sub>IND</sub>; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
Phase Jitter, PLL Mode	t <sub>jphPCleG1</sub>	PCIe Gen 1		32	86	ps (p-p)	1,2,3
	t <sub>jphPCleG2</sub>	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		1.1	3	ps (rms)	1,2
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		2.3	3.1	ps (rms)	1,2
	t <sub>jphPCleG3</sub>	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.5	1	ps (rms)	1,2,4
Additive Phase Jitter, Bypass Mode	t <sub>jphPCleG1</sub>	PCIe Gen 1		2	5	ps (p-p)	1,2,3
	t <sub>jphPCleG2</sub>	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.2	0.3	ps (rms)	1,2
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		0.8	1	ps (rms)	1,2
	t <sub>jphPCleG3</sub>	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.1	0.2	ps (rms)	1,2,4

<sup>1</sup>Applies to all outputs.

<sup>2</sup>See <http://www.pcisig.com> for complete specs

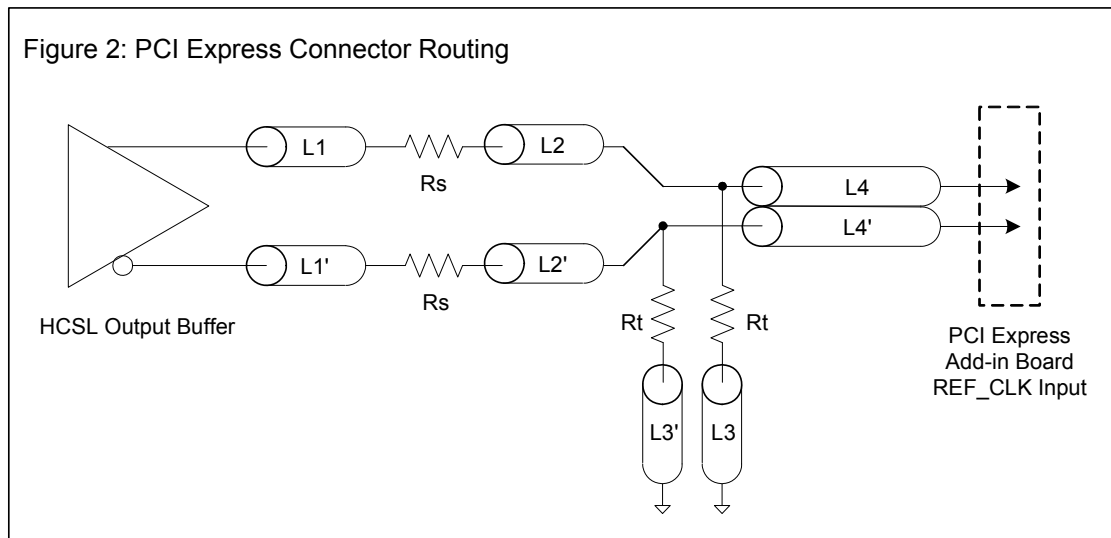
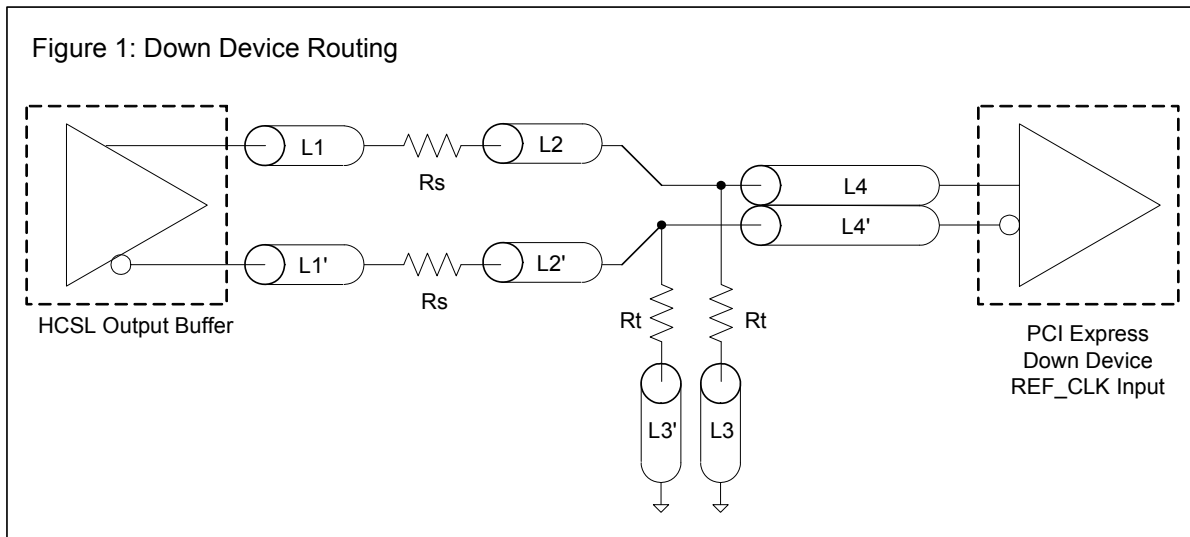
<sup>3</sup>Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

<sup>4</sup>Subject to final radification by PCI SIG.

SRC Reference Clock			
Common Recommendations for Differential Routing	Dimension or Value	Unit	Figure
L1 length, route as non-coupled 50ohm trace	0.5 max	inch	1
L2 length, route as non-coupled 50ohm trace	0.2 max	inch	1
L3 length, route as non-coupled 50ohm trace	0.2 max	inch	1
$R_s$	33	ohm	1
$R_t$	49.9	ohm	1

Down Device Differential Routing			
L4 length, route as coupled microstrip 100ohm differential trace	2 min to 16 max	inch	1
L4 length, route as coupled stripline 100ohm differential trace	1.8 min to 14.4 max	inch	1

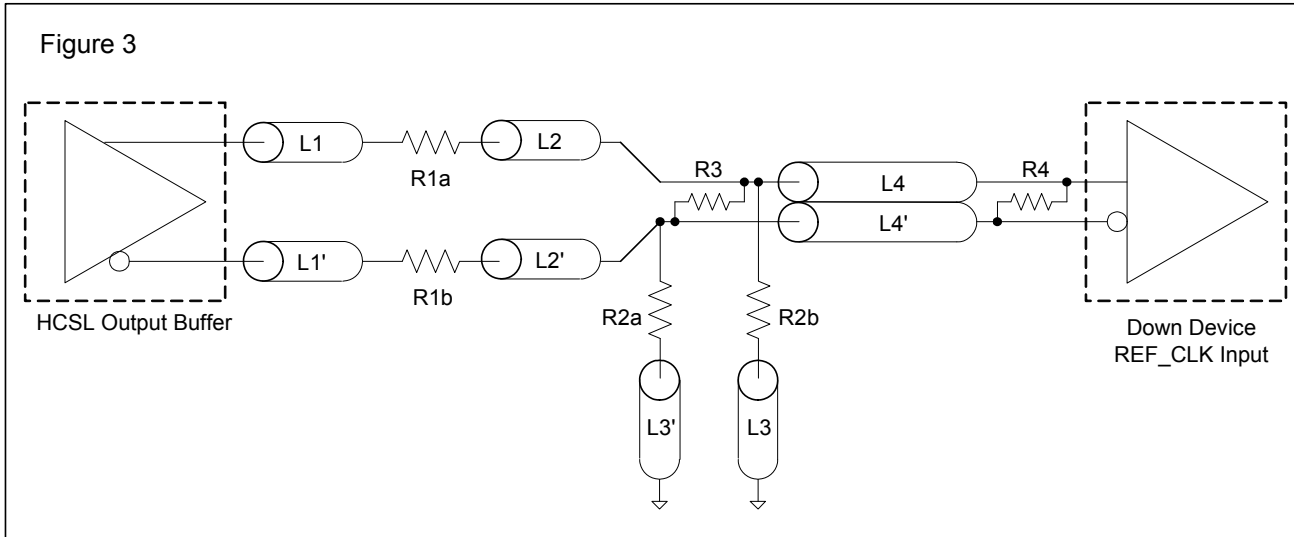
Differential Routing to PCI Express Connector			
L4 length, route as coupled microstrip 100ohm differential trace	0.25 to 14 max	inch	2
L4 length, route as coupled stripline 100ohm differential trace	0.225 min to 12.6 max	inch	2



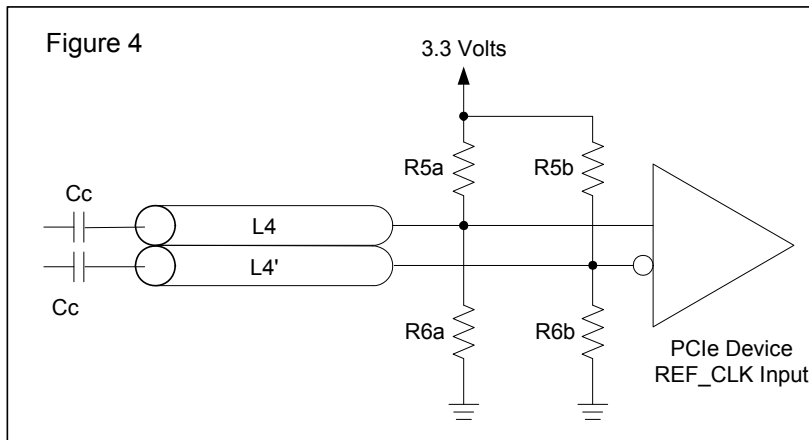
Alternative Termination for LVDS and other Common Differential Signals (figure 3)							
V <sub>diff</sub>	V <sub>p-p</sub>	V <sub>cm</sub>	R1	R2	R3	R4	Note
0.45v	0.22v	1.08	33	150	100	100	
0.58	0.28	0.6	33	78.7	137	100	
0.80	0.40	0.6	33	78.7	none	100	ICS874003i-02 input compatible
0.60	0.3	1.2	33	174	140	100	Standard LVDS

R1a = R1b = R1

R2a = R2b = R2



Cable Connected AC Coupled Application (figure 4)		
Component	Value	Note
R5a, R5b	8.2K 5%	
R6a, R6b	1K 5%	
Cc	0.1 μF	
V <sub>cm</sub>	0.350 volts	





## General SMBus serial interface information for the ICS9DB233

### How to Write:

- Controller (host) sends a start bit.
- Controller (host) sends the write address  $D4_{(H)}$
- ICS clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- ICS clock will **acknowledge**
- Controller (host) sends the data byte count = X
- ICS clock will **acknowledge**
- Controller (host) starts sending **Byte N through Byte N + X - 1**  
(see Note 2)
- ICS clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

### How to Read:

- Controller (host) will send start bit.
- Controller (host) sends the write address  $D4_{(H)}$
- ICS clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- ICS clock will **acknowledge**
- Controller (host) will send a separate start bit.
- Controller (host) sends the read address  $D5_{(H)}$
- ICS clock will **acknowledge**
- ICS clock will send the data byte count = X
- ICS clock sends **Byte N + X - 1**
- ICS clock sends **Byte 0 through byte X (if  $X_{(H)}$  was written to byte 8).**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Write Operation		
Controller (Host)		ICS (Slave/Receiver)
T	starT bit	
Slave Address $D4_{(H)}$		
WR	WRite	
Beginning Byte = N		ACK
Data Byte Count = X		ACK
Beginning Byte N	X Byte	ACK
◇		◇
◇		◇
◇		◇
Byte N + X - 1		ACK
P	stoP bit	

Index Block Read Operation			
Controller (Host)		ICS (Slave/Receiver)	
T	starT bit		
Slave Address $D4_{(H)}$			
WR	WRite		
Beginning Byte = N		ACK	
Data Byte Count = X		ACK	
RT	Repeat starT		
Slave Address $D3_{(H)}$			
RD	ReaD		
Beginning Byte = N		ACK	
Data Byte Count = X		ACK	
ACK		X Byte	
ACK			Beginning Byte N
◇			◇
◇			◇
◇			Byte N + X - 1
N	Not acknowledge		
P	stoP bit		

SMBus Table: Device Control Register, READ/WRITE ADDRESS (D4/D5)

Byte 0	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	SW_EN	Enables SMBus Control of bite 1 and 0	RW	PLL Functions controlled by SMBus registers	PLL Functions controlled by device pins	1
Bit 6	-	RESERVED		RW	-	-	X
Bit 5	-	RESERVED		RW	-	-	X
Bit 4	-	RESERVED		RW	-	-	X
Bit 3	-	RESERVED		RW	-	-	X
Bit 2	-	RESERVED		RW	-	-	X
Bit 1	-	PLL BW #adjust	Selects PLL Bandwidth	RW	Low BW	High BW	1
Bit 0	-	PLL Enable	Bypasses PLL for board test	RW	PLL bypassed (fan out mode)	PLL enabled (ZDB mode)	1

SMBus Table: Output Enable Register

Byte 1	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	RESERVED		RW	-	-	X
Bit 6	-	RESERVED		RW	-	-	X
Bit 5	-	RESERVED		RW	-	-	X
Bit 4	-	RESERVED		RW	-	-	X
Bit 3	-	RESERVED		RW	-	-	X
Bit 2	-	RESERVED		RW	-	-	X
Bit 1	-	RESERVED		RW	-	-	X
Bit 0	-	RESERVED		RW	-	-	X

SMBus Table: Function Select Register

Byte 2	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	RESERVED		RW	-	-	X
Bit 6	-	RESERVED		RW	-	-	X
Bit 5	-	RESERVED		RW	-	-	X
Bit 4	-	RESERVED		RW	-	-	X
Bit 3	-	RESERVED		RW	-	-	X
Bit 2	-	RESERVED		RW	-	-	X
Bit 1	-	RESERVED		RW	-	-	X
Bit 0	-	RESERVED		RW	-	-	X

SMBus Table: Vendor &amp; Revision ID Register

Byte 3	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	RID3	REVISION ID	R	-	-	0
Bit 6	-	RID2		R	-	-	0
Bit 5	-	RID1		R	-	-	0
Bit 4	-	RID0		R	-	-	1
Bit 3	-	VID3	VENDOR ID	R	-	-	0
Bit 2	-	VID2		R	-	-	0
Bit 1	-	VID1		R	-	-	0
Bit 0	-	VID0		R	-	-	1

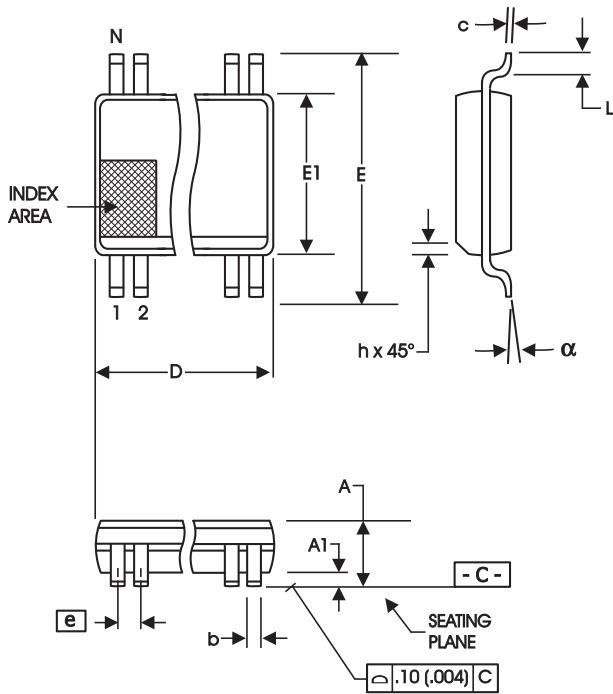
SMBus Table: DEVICE ID

Byte 4	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	Device ID = 06 Hex		R	-	-	0
Bit 6	-			R	-	-	0
Bit 5	-			R	-	-	0
Bit 4	-			R	-	-	0
Bit 3	-			R	-	-	0
Bit 2	-			R	-	-	1
Bit 1	-			R	-	-	1
Bit 0	-			R	-	-	0

SMBus Table: Byte Count Register

Byte 5	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	BC7	Writing to this register will configure how many bytes will be read back, default is 06 = 6 bytes.	RW	-	-	0
Bit 6	-	BC6		RW	-	-	0
Bit 5	-	BC5		RW	-	-	0
Bit 4	-	BC4		RW	-	-	0
Bit 3	-	BC3		RW	-	-	0
Bit 2	-	BC2		RW	-	-	1
Bit 1	-	BC1		RW	-	-	1
Bit 0	-	BC0		RW	-	-	0

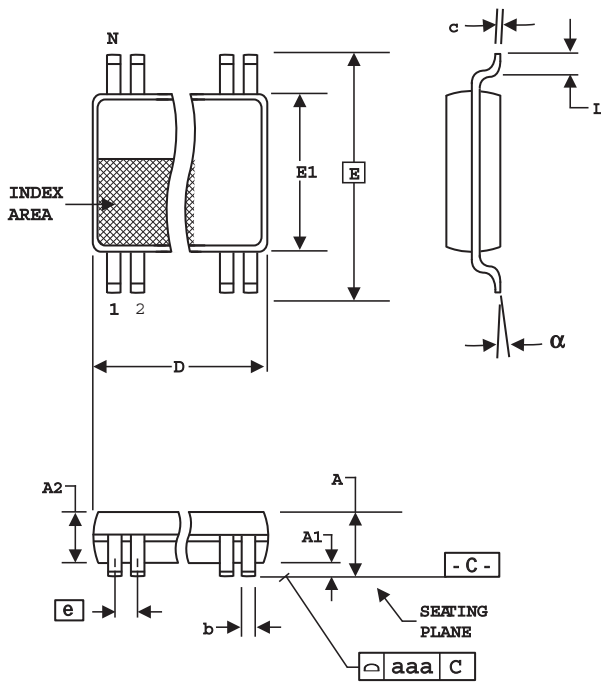
### 20-pin SSOP Package Drawing and Dimensions



20-Lead, 150 mil SSOP (QSOP)

SYMBOL	In Millimeters		In Inches	
	COMMON DIMENSIONS		COMMON DIMENSIONS	
	MIN	MAX	MIN	MAX
A	1.35	1.75	.053	.069
A1	0.10	0.25	.004	.010
A2	--	1.50	--	.059
b	0.20	0.30	.008	.012
c	0.18	0.25	.007	.010
D	SEE VARIATIONS		SEE VARIATIONS	
E	5.80	6.20	.228	.244
E1	3.80	4.00	.150	.157
e	0.635 BASIC		0.025 BASIC	
L	0.40	1.27	.016	.050
N	SEE VARIATIONS		SEE VARIATIONS	
a	0°	8°	0°	8°
ZD	SEE VARIATIONS		SEE VARIATIONS	

## 20-pin TSSOP Package Drawing and Dimensions



20-Lead, 4.40 mm. Body, 0.65 mm. Pitch TSSOP

SYMBOL	(173 mil)		(25.6 mil)	
	In Millimeters COMMON DIMENSIONS		In Inches COMMON DIMENSIONS	
	MIN	MAX	MIN	MAX
A	--	1.20	--	.047
A1	0.05	0.15	.002	.006
A2	0.80	1.05	.032	.041
b	0.19	0.30	.007	.012
c	0.09	0.20	.0035	.008
D	SEE VARIATIONS		SEE VARIATIONS	
E	6.40 BASIC		0.252 BASIC	
E1	4.30	4.50	.169	.177
e	0.65 BASIC		0.0256 BASIC	
L	0.45	0.75	.018	.030
N	SEE VARIATIONS		SEE VARIATIONS	
a	0°	8°	0°	8°
aaa	--	0.10	--	.004

### VARIATIONS

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
20	6.40	6.60	.252	.260

Reference Doc.: JEDEC Publication 95, MO-153

10-0035

## Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
9DB233AFLF	Tubes	20-pin SSOP	0 to +70°C
9DB233AFLFT	Tape and Reel	20-pin SSOP	0 to +70°C
9DB233AFILF	Tubes	20-pin SSOP	-40 to +85°C
9DB233AFILFT	Tape and Reel	20-pin SSOP	-40 to +85°C
9DB233AGLF	Tubes	20-pin TSSOP	0 to +70°C
9DB233AGLFT	Tape and Reel	20-pin TSSOP	0 to +70°C
9DB233AGILF	Tubes	20-pin TSSOP	-40 to +85°C
9DB233AGILFT	Tape and Reel	20-pin TSSOP	-40 to +85°C

"LF" after the package code are the Pb-Free configuration and are RoHS compliant.

"A" is the device revision designator (will not correlate to the datasheet revision).

## Revision History

Rev.	Who	Issue Date	Description	Page #
0.1	RDW	4/28/2010	1. Initial Release	
0.2	RDW	6/3/2010	1. Updated Pin names to match other 9DB devices CLKREQ# becomes OE# and PCIEXyy becomes DIF_yy 2. Updated maximum rise/fall time to 550ps from 700ps. This translates to a minimum slew rate of 0.67V/ns thus meeting the PCIe spec of 0.6V/ns. 3. Updated phase jitter tables to remove references to QPI. 4. Reformatted DS to have common format amongst all 9DBx33 DS. 5. Updated block diagram to match item 1	6
0.3	RDW	6/25/2010	1. Updated electrical tables to new standard format for 9DB devices. 2. Cleaned up front page text.	1, 3-6
A	RDW	6/30/2010	Released to final	
B	RDW	7/12/2010	1. Changed PWD to Default in SMBus tables.	10,11
C	RDW	4/20/2011	Changed pull down indicator from '***' to 'v '.	

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